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# 1 Current Status



### **Overview of Agreements**



- 1. Between ITRI, Kyundai and NYCU, signed in 2023
- 2. Between the Faculty of Pharmaceutical Sciences, the Graduate School of Pharmaceutical Sciences and the School of Pharmaceutical Sciences (Kyudai) and the School of Pharmaceutical Sciences (NYCU), signed in 2020
- 3. Between the School of Interdisciplinary Science and Innovation (Kyudai) and the College of Science and the College of Humanities and Social Sciences (NYCU), signed in 2019
- 4. Signed in 2023



## 2

## Inbound Exchange Program



### **Contact Information**

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2 Inbound Exchange (Kyudai→NYCU):

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3 Inbound Exchange Student Services:

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### **Application Procedure & Important Dates**

NYCU provides nomination link

Kyudai coordinator completes nomination

Kyudai students complete application

- Fall: early Mar.
- Spring: early Sep.

- Fall: end of Mar.
- Spring: end of Sep.
- Fall: Apr. 15
- Spring: Oct. 16



## **Application Documents**

No.	Item	Remarks		
1	Application Form応募用紙	Both applicant and home institution's coordinator have to sign the last page.		
2	Curriculum Vitae (CV)履歴書	Personal resume in English.		
3	Study Plan勉学計画	Please include motivation and list of intended courses.		
4	Official Transcript成績証明書	The academic records approved by the home institution and should be in English.		
5	Official Enrolment Letter 在籍証明書	The enrolment letter from the home institution or a valid student card.		
6	Passport (Info. page) パスポート	It should have at least 6 months of validity.		
7	Supporting Document (optional) TOEFL,TOEIC,など 英語は必須 北京語が出来ると良い	E.g. proof of language proficiency, certificate of awards or competitions, etc.		
8	Recommendation Letter (optional)推薦書	The letter from the home institution's coordinators or professors.		



#### The Fine Prints

- The department would review the applications and the supporting documents; each
  department reserves the right to reject or re-allocate applicants to appropriate department.
- 2. Minimum credit requirement (per semester): 9 credits for UG students; at least 2 academic courses for PG students.
- 3. Students are able to choose courses across departments or colleges. Please be aware that some professors may require the students to own basic knowledge about the courses.
- 4. Some popular courses are very competitive and exchange students may not be able to get in. It is suggested students to be more flexible about course choice.
- College of Management is limited to Final-year UG students or PG students. Most Englishtaught courses are offered in graduate level.



## 3

## Essential Semiconductor Technology (EST) Modules



### **Overview of EST Modules**

#### Semester Exchange Studies

- Students will be enrolled at NYCU in spring semester as exchange students.
- Students will choose 1 of the 2 EST modules. Each module consists of 4 courses and all courses are taught in English and worth 3 credits each.
- In addition to the 4 compulsory courses, students can also take free Mandarin courses as well as other elective courses.
- Students in this program is eligible to apply for NYCU inbound exchange scholarship for up to NTD20,000 (approx. USD625).
- Upon completion of the semester, students will be issued with a certificate of completion of EST modules along with official transcript of records.

#### 2 Summer Internship

- Students will be invited to apply for summer internship at NYCU labs or affiliated companies, including TSMC, Foxconn, Micron and MediaTek, etc. (Acceptance is not guaranteed.)
- NYCU will provide stipend of NTD55,000 (approx. USD1700) for students choosing to conduct research internships at NYCU for at least 60 days.
- Affiliated companies will provide salaries to their interns plus some may offer housing benefits or flights reimbursements.



#### **Modules & Courses**

Module 1
Device & Integration

- Semiconductor Physics & Devices (I)
- VLSI Manufacture Technology
- Green Energy Nanotechnology (taught by Prof. Samukawa, 日本人)
- Introduction to Material Science & Engineering (II)

Module 2
Process & Modules

- Semiconductor Physics and Devices (I)
- VLSI Manufacture Technology
- Principles & Applications of Materials Characterization Techniques
- Diffusion



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## Inbound Internship Program



### Internship Types & Opportunities

### 1 Research at NYCU

- Current list of possible host supervisors can be found <u>here</u>.
- Students can also contact other professors at NYCU for research opportunities.
- Duration: at least 60 days to receive NYCU stipend.

### 2 Internship at Industry

- Current affiliated companies include TSMC, HHRI (Foxconn), Micron and MediaTek and E.SUN Bank.
- For a list of current internship openings can be found <a href="here">here</a>.
- Duration: 8 weeks or as stipulated by the host company.



Company	NYCU	TSMC	E.SUN Bank	MediaTek Inc.	Micron Technology	HHRI (Foxconn)		
NYCU Stipend* (for 2 months; in NTD)	NTD 55,000 (before tax and bank handing charge)							
Monthly Salary (in NTD)	×	Depends on hiring division	30,000	Negotiable	Negotiable	Negotiable		
Economy Class Return Flights	×	Depends on hiring division	Depends on hiring division	V	Depends on hiring division	Depends on hiring division		
Housing	Fee-paying on- campus dormitory	V	X	V	Qualified applicants may apply for dormitory in Taichung or housing subsidy in Taoyuan	Depends on hiring division		
Required Mandarin Proficiency	Nil	Oral communication ability will be a plus	Fair	Nil	Nil	Nil		
Level of Study Accepted	Bachelor Master PhD.	Bachelor (senior) Master (preferred) PhD. (preferred)	Bachelor Master	Master PhD.	Bachelor (Senior), Master, PhD.	Bachelor Master PhD.		
Internship Duration	At least 60 days	June – August, 2024 (Detailed schedule depends on corporate partner)						

Senior=4年生

